

- ★ Super Low Gate Charge
- ★ Green Device Available
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

Product Summary



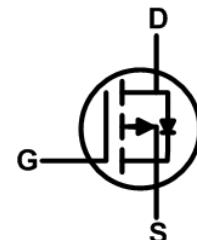
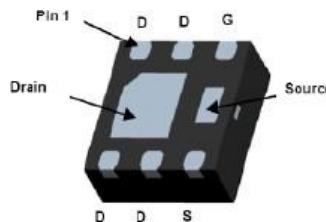
BVDSS	RDS(ON)	ID
-15V	6.5mΩ	-25A

Description

The XR25P01M is the high cell density trenched P-ch MOSFETs, which provide excellent RDS(ON) and gate charge for most of the synchronous buck converter applications.

The XR25P01M meet the RoHS and Green Product requirement with full function reliability approved.

DFN2020-6L Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-15	V
V_{GS}	Gate-Source Voltage	± 12	V
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, $V_{GS} @ -4.5V^1$	-25	A
$I_D @ T_C = 70^\circ C$	Continuous Drain Current, $V_{GS} @ -4.5V^1$	-18	A
I_{DM}	Pulsed Drain Current ²	-120	A
$P_D @ T_C = 25^\circ C$	Total Power Dissipation ³	18	W
$P_D @ T_C = 70^\circ C$	Total Power Dissipation ³	12	W
T_{STG}	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹	156	°C/W
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹ ($t \leq 10s$)	---	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	4.2	°C/W

Electrical Characteristics ($T_J=25^\circ C$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-15	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to $25^\circ C, I_D=-1mA$	---	-0.012	---	$V/\text{ }^\circ C$
$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance ²	$V_{GS}=-4.5V, I_D=-15A$	---	6.5	9	$m\Omega$
		$V_{GS}=-2.5V, I_D=-5A$	---	9.5	13	
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=-250\mu A$	-0.4	-0.7	-1.0	V
$\Delta V_{GS(\text{th})}$	$V_{GS(\text{th})}$ Temperature Coefficient		---	2.94	---	$mV/\text{ }^\circ C$
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=-12V, V_{GS}=0V, T_J=25^\circ C$	---	---	1	μA
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 12V, V_{DS}=0V$	---	---	± 100	nA
g_{fs}	Forward Transconductance	$V_{DS}=-5V, I_D=-10A$	---	43	---	S
Q_g	Total Gate Charge (-4.5V)	$V_{DS}=-10V, V_{GS}=-4.5V, I_D=-10A$	---	35	---	nC
Q_{gs}	Gate-Source Charge		---	5.0	---	
Q_{gd}	Gate-Drain Charge		---	10	---	
$T_{d(on)}$	Turn-On Delay Time		---	12.0	---	ns
T_r	Rise Time	$V_{DD}=-10V, V_{GS}=-4.5V, R_G=3.3\Omega, I_D=-10A$	---	40.0	---	
$T_{d(off)}$	Turn-Off Delay Time		---	30	---	
T_f	Fall Time		---	10	---	
C_{iss}	Input Capacitance	$V_{DS}=-15V, V_{GS}=0V, f=1MHz$	---	2800	---	pF
C_{oss}	Output Capacitance		---	690	---	
C_{rss}	Reverse Transfer Capacitance		---	590	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current ^{1,4}	$V_G=V_D=0V$, Force Current	---	---	-25.0	A
I_{SM}	Pulsed Source Current ^{2,4}		---	---	---	A
V_{SD}	Diode Forward Voltage ²	$V_{GS}=0V, I_S=-1A, T_J=25^\circ C$	---	---	-1.2	V
t_{rr}	Reverse Recovery Time	$ I_F =-10A, dI/dt=100A/\mu s, T_J=25^\circ C$	---	27	---	nS
Q_{rr}	Reverse Recovery Charge		---	17.8	---	nC

Note :

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
2. The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
3. The power dissipation is limited by $150^\circ C$ junction temperature
4. The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

P-Ch 15V Fast Switching MOSFETs

Typical Characteristics

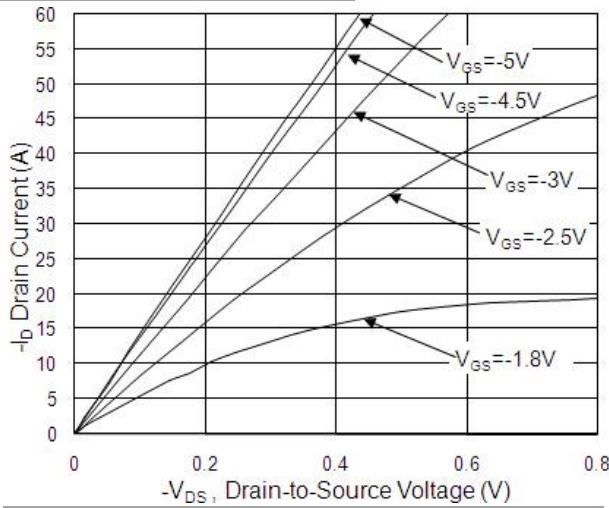


Fig.1 Typical Output Characteristics

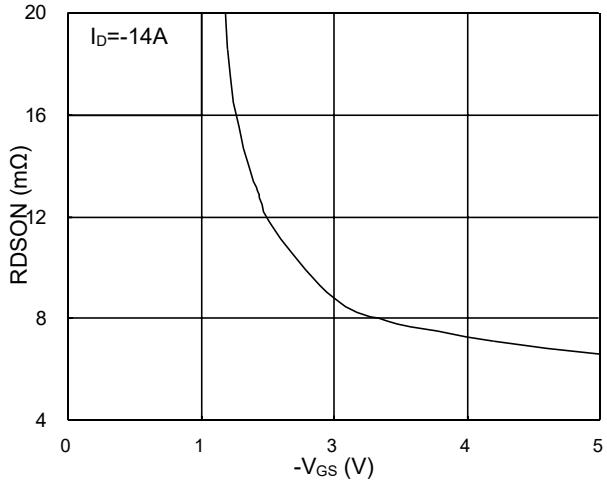


Fig.2 On-Resistance vs. G-S Voltage

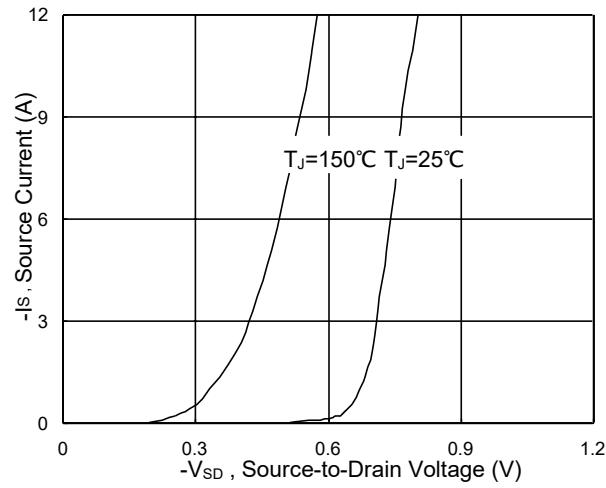


Fig.3 Forward Characteristics of Reverse

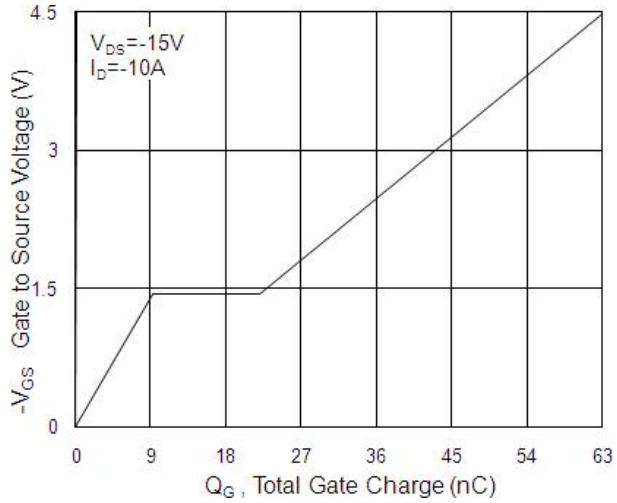
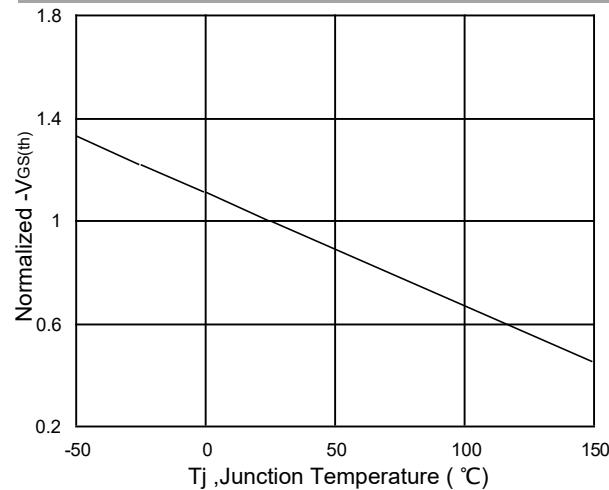
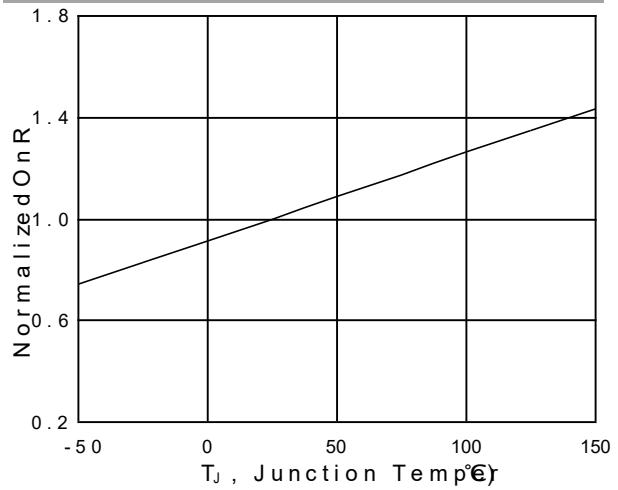


Fig.4 Gate-charge Characteristics

Fig.5 Normalized $V_{GS(th)}$ vs. T_J Fig.6 Normalized $R_{DS(on)}$ vs. T_J

P-Ch 15V Fast Switching MOSFETs

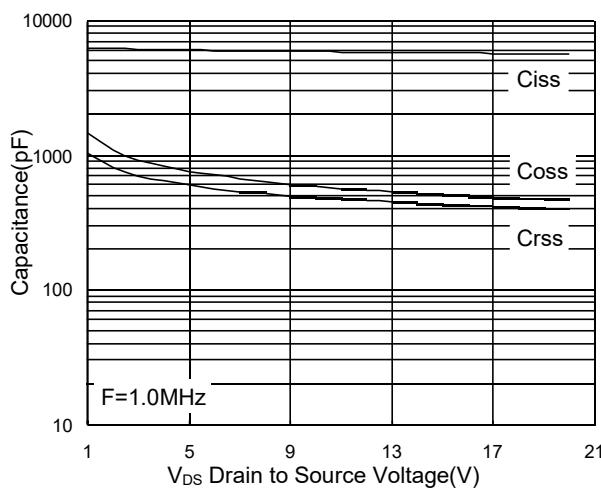


Fig.7 Capacitance

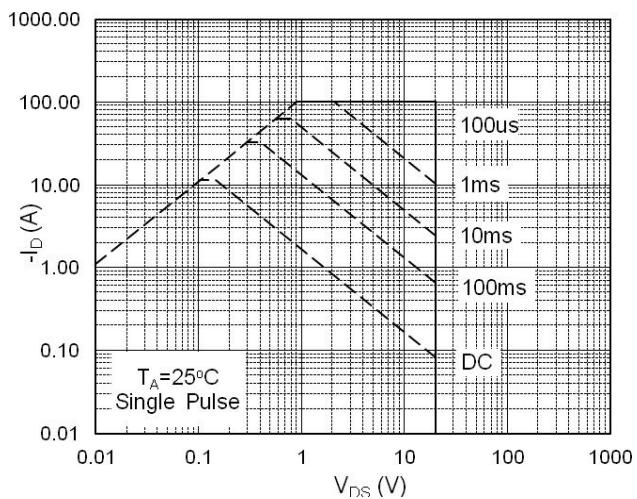


Fig.8 Safe Operating Area

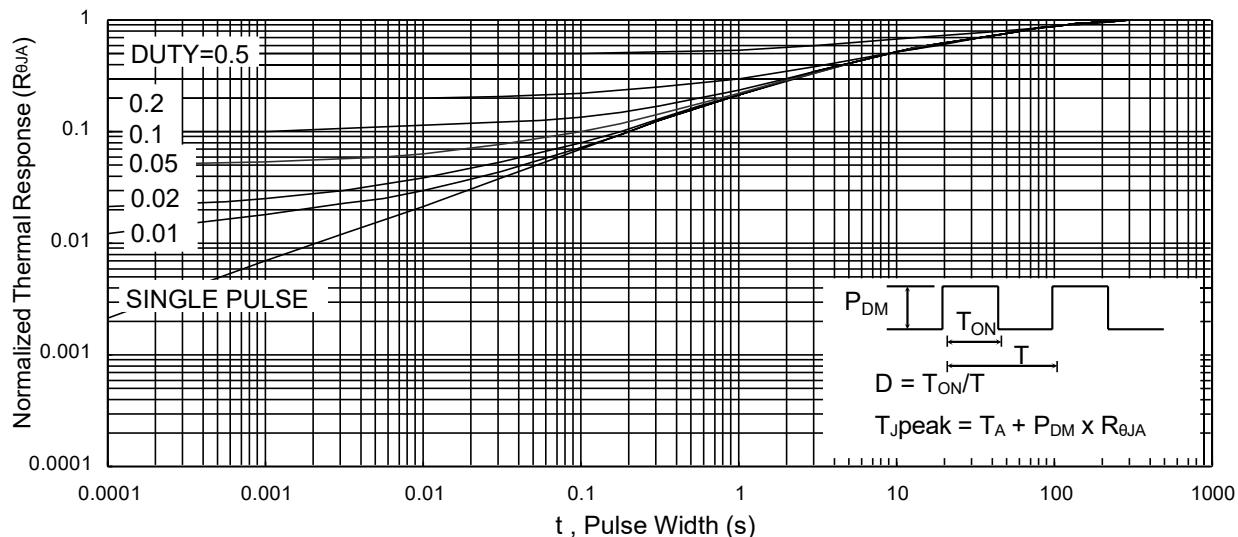


Fig.9 Normalized Maximum Transient Thermal Impedance

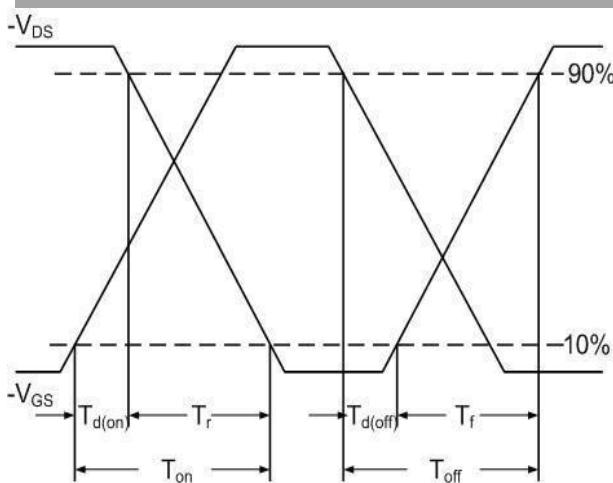


Fig.10 Switching Time Waveform

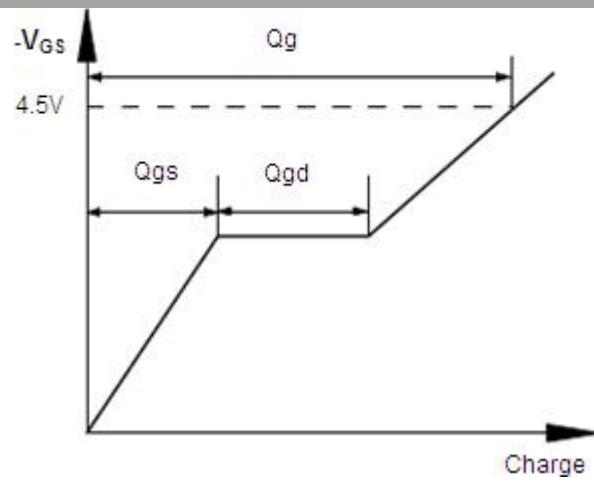
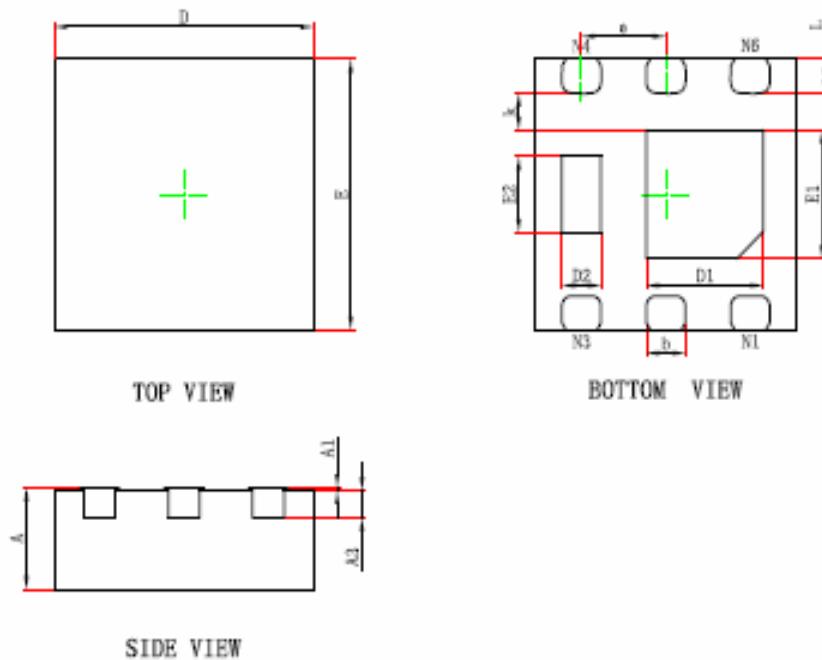


Fig.11 Gate Charge Waveform

DFN2020-6L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.700	0.800	0.028	0.031
A1	0.000	0.050	0.000	0.002
A3	0.203REF.		0.008REF.	
D	1.924	2.076	0.076	0.082
E	1.924	2.076	0.076	0.082
D1	0.800	1.000	0.031	0.039
E1	0.850	1.050	0.033	0.041
D2	0.200	0.400	0.008	0.016
E2	0.460	0.660	0.018	0.026
k	0.200MIN.		0.008MIN.	
b	0.250	0.350	0.010	0.014
e	0.650TYP.		0.026TYP.	
L	0.174	0.326	0.007	0.013